

	Hits	Search Text	DBs
1	6	(("4697203") or ("5734156") or ("5818094") or ("6075237") or ("6117193") or ("6291884")) .PN.	US-PGPUB; USPAT
2	3	(("6873024") or ("6781244") or ("6607941")) .PN.	US-PGPUB; USPAT
3	40	((semiconductor or wafer or substrate) same (die or circuit\$5) same (cover or lid or plate) same (pattern\$4 or (transparent near9 region) or \$6lithograph\$6) same ((bond or contact) near9 pad) same (support or structure or strut or mount\$4)) and (bump same (solder or gold)) and (encapsulat\$5 same pack\$5) and (electrical\$4 same (coupl\$4 or contact\$4)) and (scrib\$4 or singulat\$4 or dic\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
4	46	((semiconductor or wafer or substrate) same (die or circuit\$5) same (cover or lid or plate) same (pattern\$4 or (transparent near9 region) or \$6lithograph\$6) same ((bond or contact) near9 pad) same (support or structure or strut or mount\$4)) and (bump same (solder or gold)) and (encapsulat\$5 same pack\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
5	2	shellop near9 technology	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
6	124	((semiconductor or wafer or substrate) near9 (die or circuit\$5 or (integrated near9 circuit\$4)) near12 (cover or lid or plate) near19 pattern\$4 near9 ((transparent near9 region) or \$6lithograph\$6 or photolithograph\$6))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
7	0	((semiconductor or wafer or substrate) near9 (die or circuit\$5 or (integrated near9 circuit\$4)) near12 (cover or lid or plate) near19 pattern\$4 near9 ((transparent near9 region) or \$6lithograph\$6 or photolithograph\$6)) same encapsulat\$4 same packa\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
8	10	((semiconductor or wafer or substrate) near9 (die or circuit\$5 or (integrated near9 circuit\$4)) near12 (cover or lid or plate) near19 pattern\$4 near9 ((transparent near9 region) or \$6lithograph\$6 or photolithograph\$6)) and (encapsulat\$4 near9 packag\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB
9	107	((semiconductor or wafer or substrate) near9 (die or circuit\$5 or (integrated near9 circuit\$4)) near12 (cover or lid or plate) near13 ((transparent near9 region) or \$6lithograph\$6 or pattern\$4 or photolithograph\$6)) and (encapsulat\$4 near9 packag\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB